

Applic. No. : 10/090,289

Remarks:

Consideration of the application is requested.

Claims 1-22 are now in the application. Claims 1 and 15-17 have been amended. Claims 21-22 have been added.

In deference to the restriction requirement on page 2 of the above-identified Office action, Applicant elects under traverse product claims 1-14 for prosecution at this time.

In item 2 on page 2 of the Office action, the Examiner stated that "the devices of the group I invention could be made by processes materially different from those of the Group II invention. For example, in claim 1, the electronic component may have a wiring board with center apertures formed thereon."

Applicant does not quite understand how producing an electronic component with a wiring board with **center** apertures must or could be made by a materially different process as recited in claim 15. Notwithstanding, claims 1 and 15 have been appropriately amended in view of the Examiner's restriction requirement.

It is accordingly believed that the claims meet the "one invention" requirement of 35 U.S.C. § 121 and, consequently, the Examiner is requested to reconsider the restriction requirement. The above-noted changes to claims 1 and 15 are

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provided solely for the purpose to overcome the Examiner's restriction requirement. The changes are neither provided for overcoming the prior art nor do they narrow the scope of the claims for any reason related to the statutory requirements for a patent.

In view of the foregoing, the early issuance of an Action on the merits, and the allowance of the claims are solicited.

Should the Examiner maintain the restriction requirement, Applicant requests a rejoinder under MPEP §821.04 for the non-elected method claims, claims 15-22, at an appropriate later date.

If an extension of time is required, petition for extension is herewith made.

Enclosed is Counsel's payment in the amount of \$ 36.00 for the extra two claims in excess of twenty in accordance with 37 CFR 1.16(c).

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Please charge any other fees which might be due with respect to Sections 1.16 and 1.17 to the Deposit Account of Lerner and Greenberg, P.A., No. 12-1099.

Respectfully submitted,



For Applicant

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March 11, 2003

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Version with markings to show changes made:

Claim 1 (amended). An electronic component, comprising:

at least two wiring boards stacked on top of one another and substantially parallel to one another, and at least one of said at least two wiring boards having apertures formed therein;

at least two semiconductor chips each mounted on a respective wiring board of said at least two wiring boards and electrically connected to said respective wiring board; and solder connections[, said wiring boards stacked one on top of another substantially parallel to one another and interconnected] mechanically and electrically [by said soldered connections resulting in] interconnecting said at least two stacked wiring boards, said soldered connections extending through said apertures in at least one of said at least two stacked wiring boards and over one or more levels of said at least two stacked wiring boards.

Claim 15 (amended). A method for producing an electronic component, which comprises the steps of:

providing at least two wiring boards having electrical contacts disposed thereon and at least two semiconductor chips

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each mounted on and electrically connected to a respective wiring board of the at least two wiring boards, and at least one of the wiring boards having [near-edge] apertures formed therein;

[mounting semiconductor chips on the wiring boards with a respective semiconductor chip mounted on each of said wiring boards, and electrically connecting the respective semiconductor chip to a respective wiring board of the wiring boards;

applying supporting points to rear sides of the wiring boards facing away from the semiconductor chips;]

depositing solder in the [near-edge] apertures of the wiring boards[, with the electrical contacts adjoining the near-edge apertures];

stacking [in] the wiring boards substantially parallel [the wiring boards with the semiconductor chips mounted on them, a rear side of the respective semiconductor chip coming to bear on a respective one of the supporting points]; and

melting the solder resulting in [mechanical and electrical connections being formed between adjoining levels of the wiring boards forming a stack] solder connections mechanically and electrically interconnecting the at least two stacked wiring boards, the solder connections extending through the

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apertures in at least one of the at least two wiring boards  
and over one or more levels of the at least two stacked wiring  
boards.

Claim 16 (amended). The method according to claim 15, which comprises providing the solder in the [near-edge] apertures in a form of solder balls having a smaller diameter than the [near-edge] apertures.

Claim 17 (amended). The method according to claim 15, which comprises providing the solder in the [near-edge] apertures in a form of solder paste.

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